

Low-Power Hall Switch



General Description

FD2H003B*-G1 is a low-power integrated Hall switch designed to sense the applied magnetic flux density and give a digital output, which indicates the present condition of the magnitude sensed. One example of the applications is the on/off switch in cellular flip-phones.

The micro power design is especially suitable for battery-operated systems such as cellular phones or laptop computers, in which power consumption is one major concern. The typical power consumption of FD2H003B*-G1 is below 10 μ W at 2.7V.

The magnetic switching points are precise and insensitive to process and temperature variations.

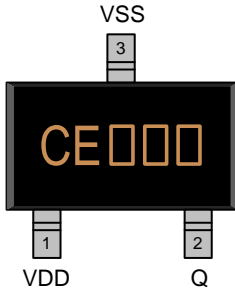
For FD2H003B*-G1, the output will be at the “high” level when no magnetic field is applied. When the applied magnetic flux density is stronger than the switching threshold, the output would be at the “low” level.

Features

- Micro power consumption
- 1.8V to 5.5V battery operation
- Chopper Amplifier based design:
Insensitive to noise and offset caused by process variations, operating temperatures and mechanical stress Digital output
- CMOS process
- CMOS output stage : no external pull-up resistor needed

Pin Descriptions

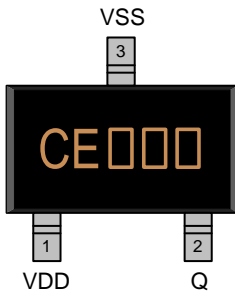
FD2H003BYR-G1



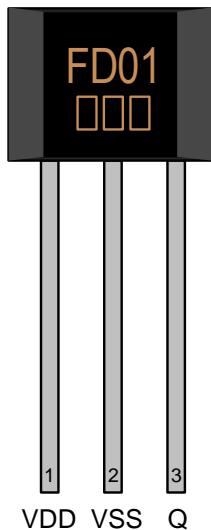
Name	I/O	Description
VDD	P	Positive supply
Q	O	Open Drain output
VSS	G	Ground

Legend: I=input, O=output, I/O=input/output, P=power supply, G=ground

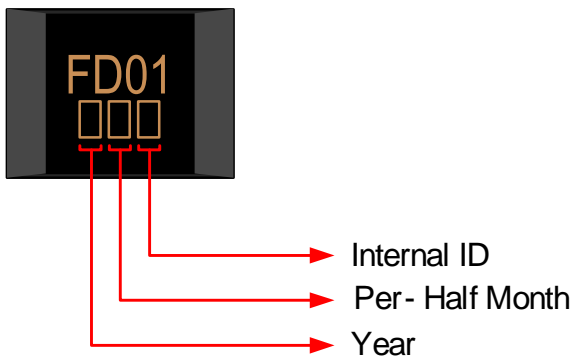
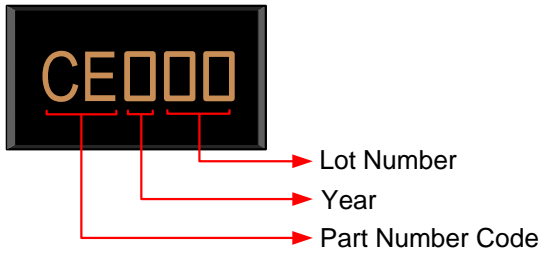
FD2H003BaR-G1



FD2H003BH-G1



Marking Information



Halogen Free: Halogen free product indicator

Lot Number: Wafer lot number's last two digits

For Example → Lot : 123456 → XXx-56L

Internal ID: Internal Identification Code

Per-Half Month: Production period indicator in half month time unit

For Example : A → First Half Month of January

B → Second Half Month of January

C → First Half Month of February

D → Second Half Month of February

Year: Production year's last digit

Part Number Code: Part number identification code for this product.

Block Diagram

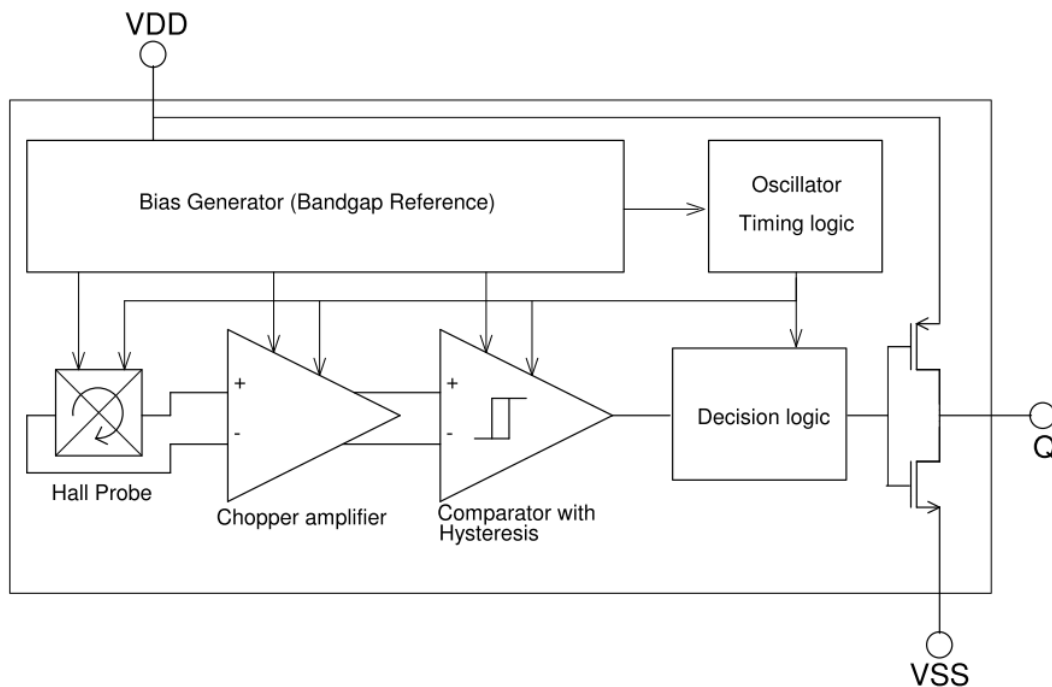


Figure.1

Functional Descriptions

Refer to the block diagram (Figure.1), FD2H003-LF is composed of the following building blocks:

- **Bias Generator**

The bias generator provides precise, temperature and process insensitive current sources for both the Hall plate and the chopper amplifier. These current sources in turn guarantee proper operation of the chip and precise switching thresholds under all kinds of environments specified in the specification.

- **Oscillator + Timing logic**

The built-in oscillator provides the clock signal, which is taken by the timing logic to determine the periods of the operating phase and the stand-by phase. Typically the operating time is about 60us and the stand-by time is 150ms. Using such a clocking scheme, the average power consumption is almost equal to that in the stand-by phase, which is under 10μW at 2.7V.

- **Chopper Amplifier**

To achieve a higher resolution the chopper amplifier structure is adopted in this design. Use of this structure dynamically removes both the offset and flicker noise at the same time.

- **Comparator with Hysteresis Control**

This block determines the switching threshold of the Hall switch in different situations.

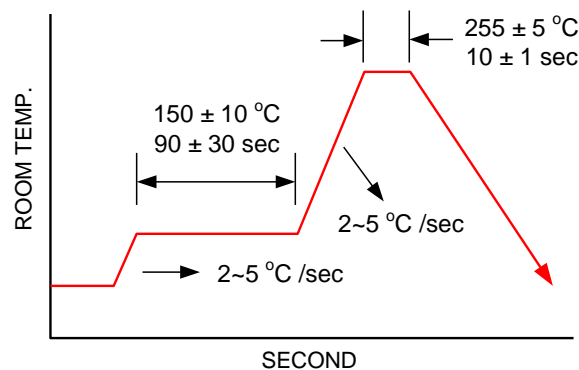
Ordering information

Part Number	Operating Temperature	Part Number Code	Package	Description	MOQ
FD2H003BYR-G1	-20 °C to +105 °C	CE	SOT23	±25G (B)	3000ea / Reel
FD2H003BaR-G1	-20 °C to +105 °C	CE	TSOT23	±25G (B)	3000ea / Reel
FD2H003BH-G1	-20 °C to +105 °C	-	SIP3	±25G (B)	1000ea / Bag

Absolute Maximum Ratings

Parameter	Conditions	Min.	Max.	Unit
Ambient Operating Temperature	-	-40	85	°C
Storage Temperature	-	-40	150	°C
DC Supply Voltage	-	1.8	5.5	V
Supply Current	-	-1	2.5	mA
Programming Pin Voltage (only available for FD2H003B*-G1)	With respect to VSS	-0.3	5.5	V
Magnetic Flux Density	-		unlimited	G
Lead Temperature	10sec	-	260	°C

IR Re-flow Soldering Curve



IR-Reflow Soldering Condition

Figure. 2

Operating Conditions

Parameter	Conditions	Min.	Typ.	Max.	Unit
Supply Voltage	-	1.8	2.7	5.5	V
Output Voltage	-	-0.3	2.7	5.5	V
Ambient Temperature	-	-40	25	85	°C

Electrical Characteristics

Parameter	Conditions	Min.	Typ.	Max.	Unit
Average Supply Current	-	-	3 ¹	20	μA
Average Supply Current (operating phase)	-	-	1.1 ¹	-	mA
Average Supply Current (stand-by phase)	-	-	2.5 ¹	-	μA
Output High Voltage(VOH)	Io=-0.5mA	VDD-0.4V	-	-	V
Output Low Voltage(VOL)	Io=+0.5mA	-	-	0.4V	V
Output Leakage Current	-	-	0.01	-	μA
Operating time	-	-	60	-	μs
Standby time	-	-	150	-	ms
Duty cycle	-	-	0.04	-	%

1. operating voltage 2.7V

Magnetic Characteristics

Parameter	Conditions	Min.	Typ.	Max.	Unit
Operate Points (B _{OP})	-	15	25	35	G
Hysteresis	-	5	10	15	G

Magnetic Flux

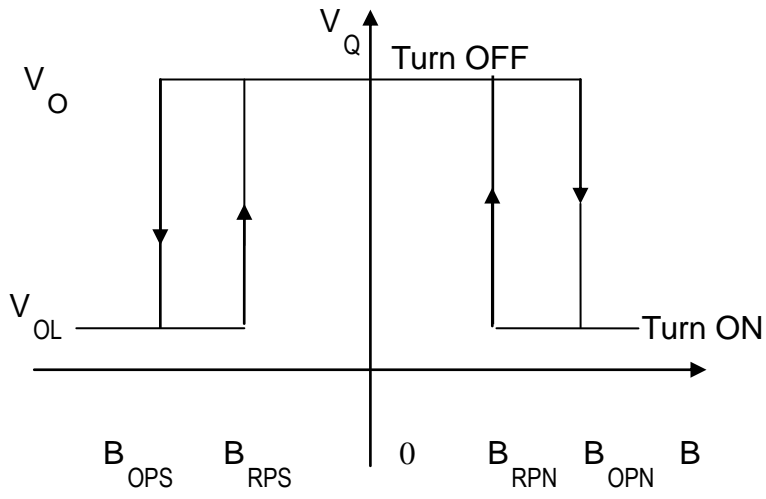


Figure 3 . FD2H003B*-G1

Typical Characteristics

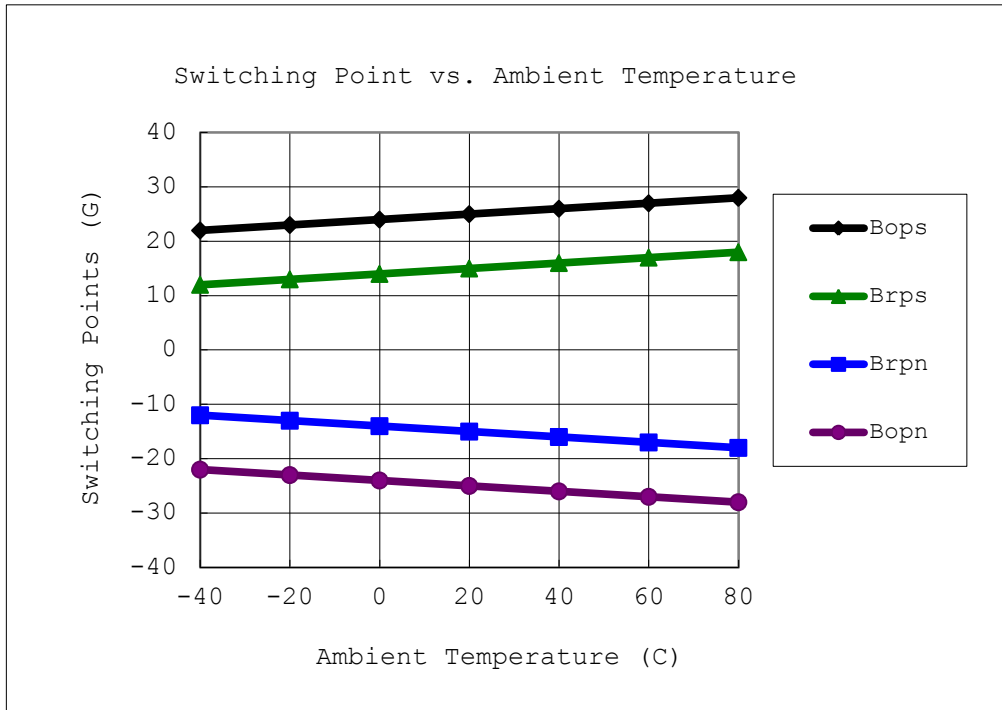


Figure.4 Magnetic Switch Points Versus Ambient Temperature (VDD=2.7V)

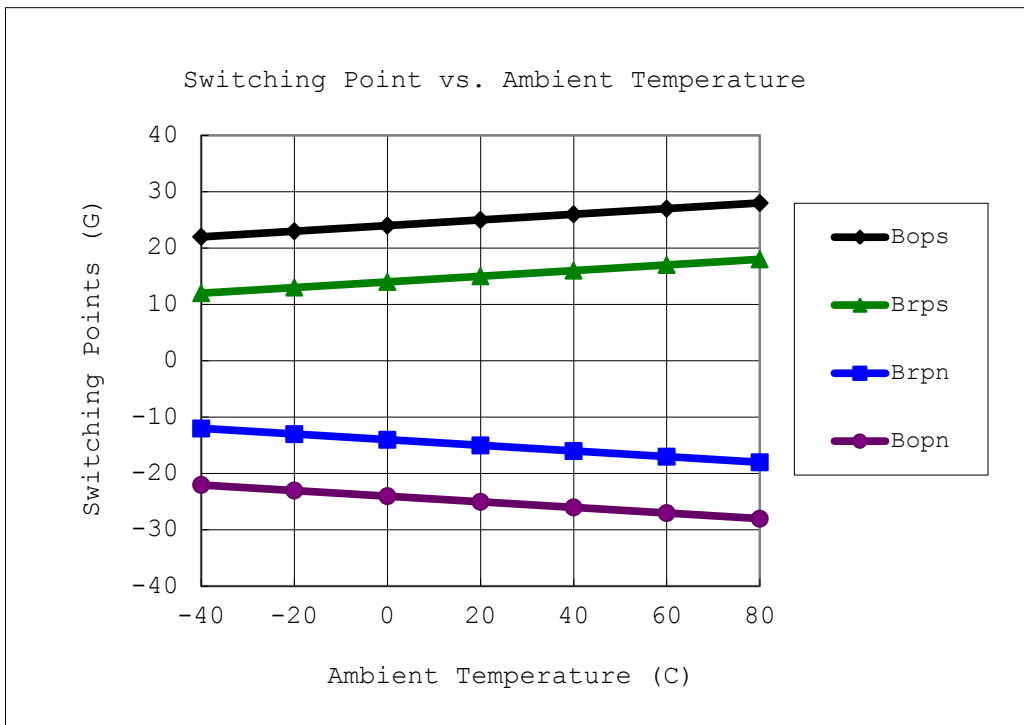


Figure.5 Magnetic Switch Points Versus Supply Voltage (Ta=25C degree)

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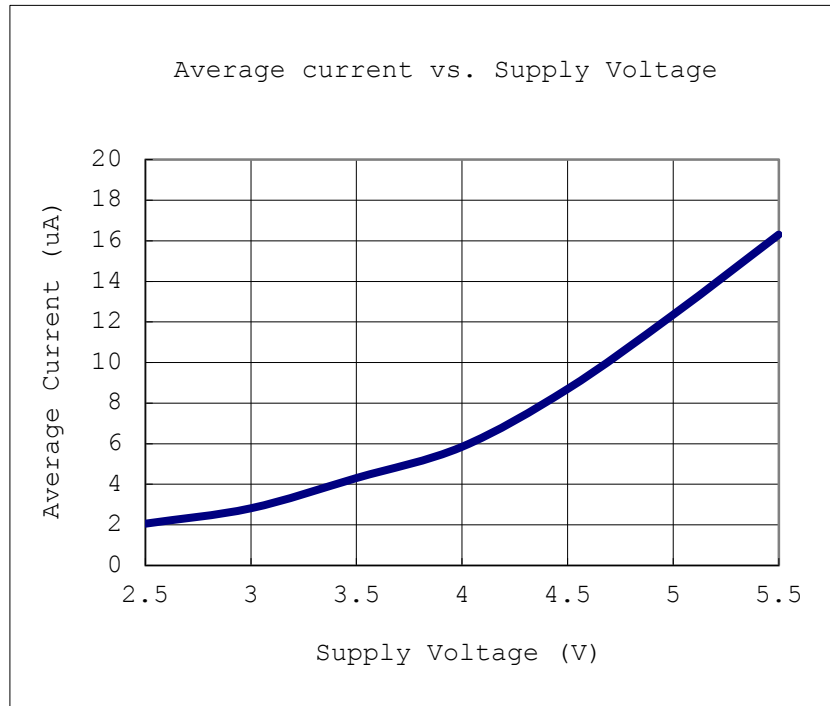


Figure.6 Average Current Versus Supply Voltage (Ta=25C degree)

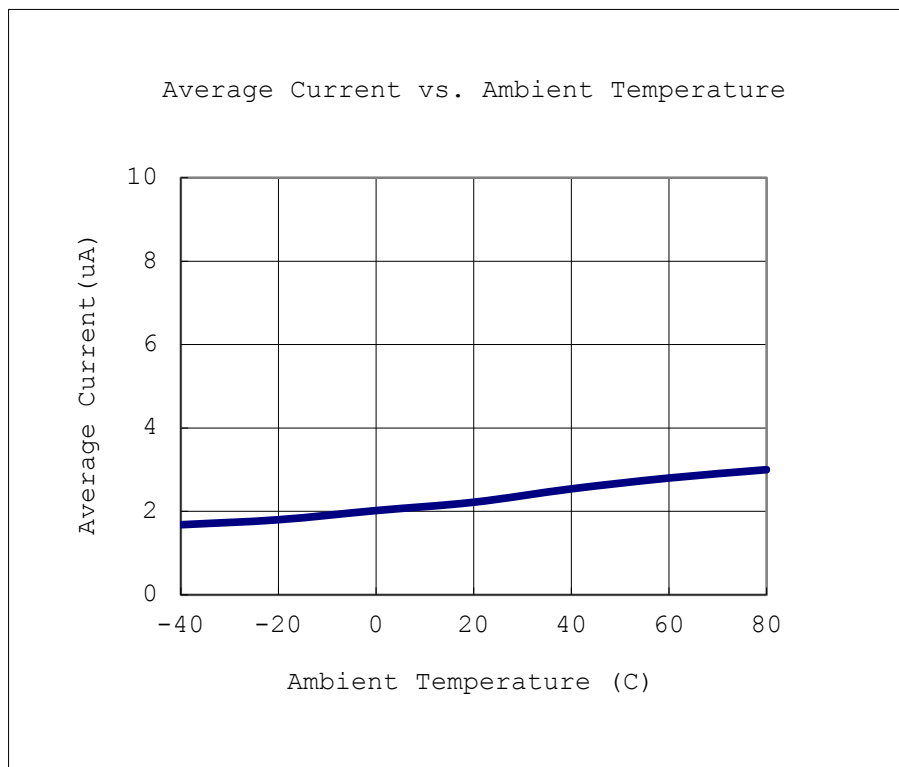


Figure.7 Average Current Versus Ambient Temperature (VDD=2.7V)

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Application Circuit Reference

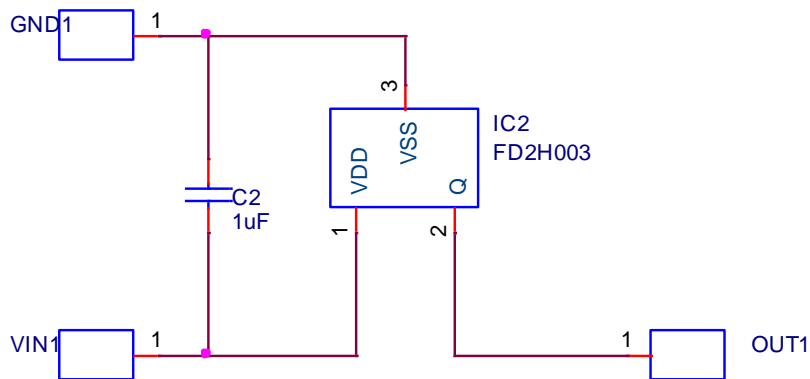


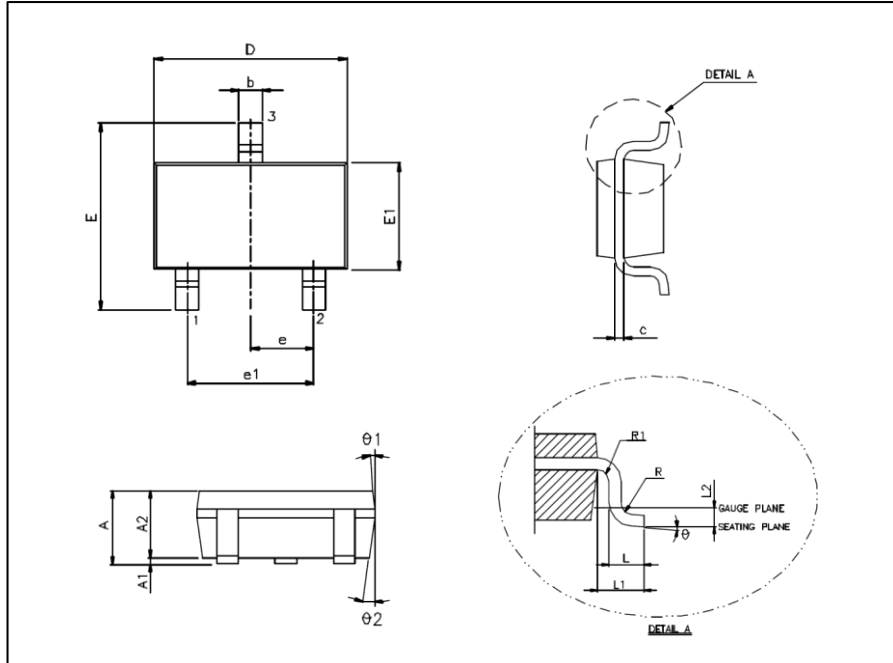
Figure.7

NOTE:

1. *R1 is for power supply filtering function, and must be placed as close to IC1 as possible.*

Package Outline

SOT23(FD2H003BYR-G1)

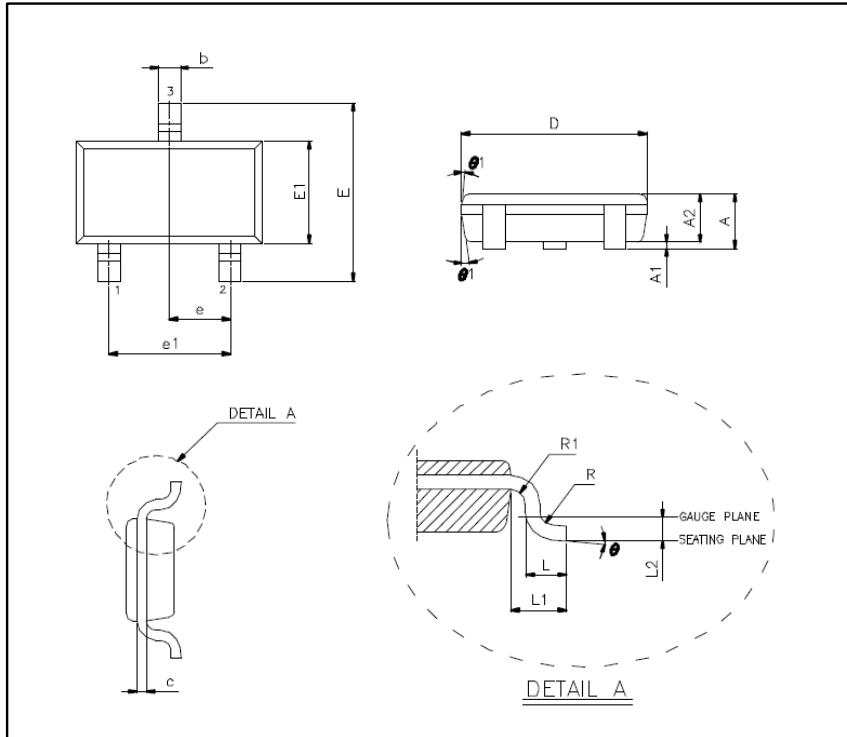


Unit: mm

Symbols	Min. (mm)	Nom. (mm)	Max. (mm)
A	-	-	1.45
A1	-	-	0.15
A2	0.90	1.15	1.30
b	0.30	-	0.50
c	0.08	-	0.22
D	2.90 BSC.		
E	2.80 BSC		
E1	1.60 BSC		
e	0.95 BSC		
e1	1.90 BSC		
L	0.30	0.45	0.60
L1	0.60 REF.		
L2	0.25 BSC		
R	0.10	-	-
R1	0.10	-	0.25
θ°	0°	4°	8°
$\theta1^\circ$	5°	10°	15°

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TSOT-23L(FD2H003BaR-G1)

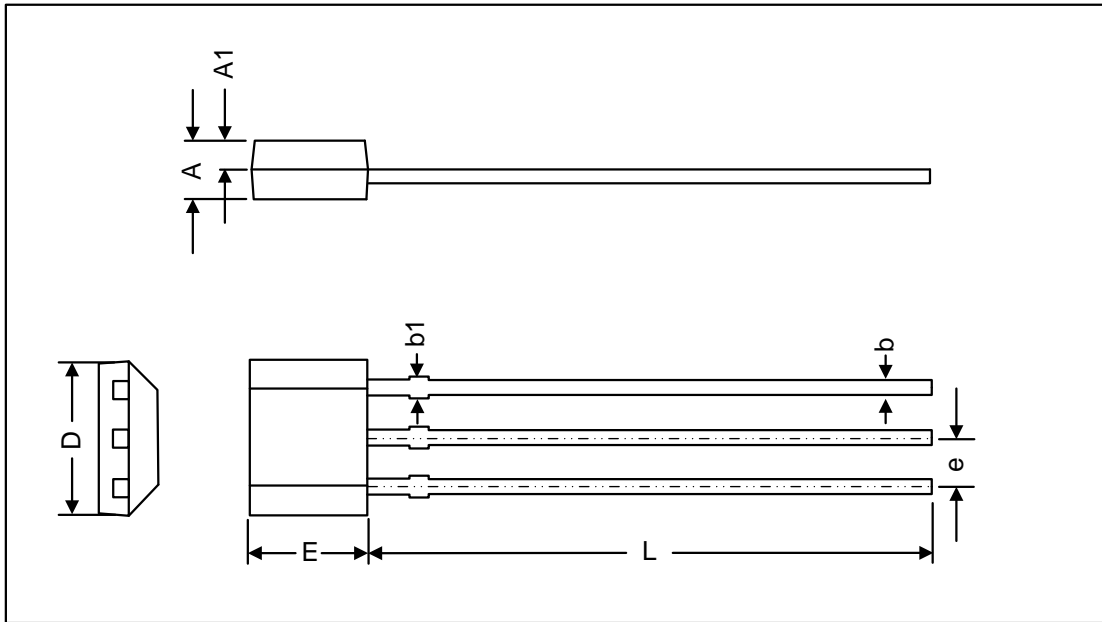


Unit: mm

Symbols	Dimension In Millimeters		
	Min	Nom	Max
A	0.750	-	0.800
A1	0.025	-	0.050
A2	0.700	0.750	0.775
b	0.350	-	0.500
c	0.100	-	0.200
D	2.800	2.900	3.000
E	2.600	2.800	3.000
E1	1.500	1.600	1.700
e	0.950 BSC		
e1	1.900 BSC		
L	0.370	0.450	0.600
L1	0.600 REF		
L2	0.250 BSC		
R	0.100	-	-
R1	0..100	-	0.250
θ	0°	4°	8°
θ_1	4°	10°	12°

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SIP-3L (FD2H003BH-G1)



Unit: mm

Symbols	Min. (mm)	Nom. (mm)	Max. (mm)
A	1.245	-	1.753
A1	0.75REF		
b	0.33	-	0.56
b1	0.54 REF		
D	3.85	-	4.2
E	2.87	-	3.124
L	13.5	-	15.6
e	1.27 REF		

Note:

1. Dimension "D" does not include molding flash, protrusions or gate burrs.
2. Dimension "E" does not include interlead flash, protrusions.